

Octal Line Driver

FEATURES

- Eight Single Ended Line Drivers in One Package
- Meets EIA Standards EIA232E/V.28, EIA423A and CCITT V.10/X.26
- Single External Resistor Controls
 Slew Rate
- Wide Supply Voltage Range
- Tri-State Outputs
- Output Short-Circuit Protection

ABSOLUTE MAXIMUM RATINGS (Note 1)

V+ (Pin 20)
V- (Pin 11)–15V
PLCC Power Dissipation, TA = 25°C (Note 2) 1000 mW
DIP Power Dissipation, TA = 25°C (Note 2) 1250 mW
Input Voltage
Output Voltage
Slew Rate Resistor
Storage Temperature
Note 1: All voltages are with respect to ground, pin 18.

Note 2: Consult Packaging Section of Databook for thermal limitations and considerations of packages.

DESCRIPTION

The UC5170C is a single-ended octal line driver designed to meet both standard modem control applications (EIA232E/V.28), and long line drive applications (EIA423A/V.10/X.26). The slew rate for all eight drivers is controlled by a single external resistor. The slew rate and output levels in Low Mode are independent of the power variations.

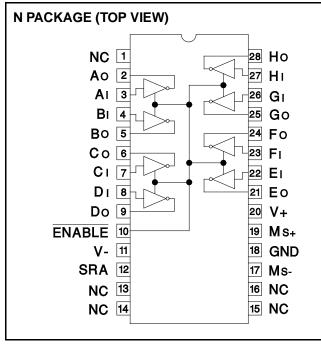
Mode selection is easily accomplished by taking the select pins (Ms+ and Ms-) to ground for low output mode (EIA232E/V.28 and EIA423A/V.10) or to their respective supplies for high mode (EIA232E/V.28). High mode should only by used to drive adapters that take power from the control lines, or applications using high threshold receivers.

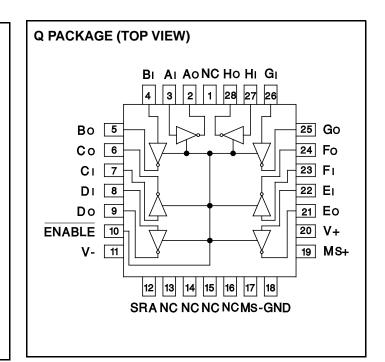
FUNCTIONAL TABLE

INP	UTS	OUTPUTS				
		HIGH	LOW			
EN	DATA	EIA-232E ⁽²⁾	EIA423A+EIA232E			
0	0	(V+)-3V	5V to 6V			
0	1	(V-)-3V	-5V to -6V			
1	Х	High Z	High Z			

Note 2: Minimum output swings.

CONNECTION DIAGRAMS





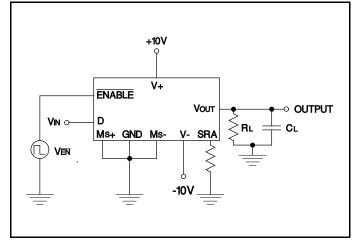
DC ELECTRICAL CHARACTERISTICS:	Unless otherwise stated these specifications hold for $ V+ = V- = 10V$,
	0 < TA < +70°C, Ms+ = Ms– = 0V, Rsra = +10k, Ta =Tj.

$0 < TA < +70^{\circ}C$, Ms+ = Ms- = 0V, RsrA = +10k, TA =TJ.							
PARAMETERS	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS	
POWER SUPPLY REQUIREMENTS							
V+ Range			9		15	V	
V- Range			-9		-15	V	
V+ Supply Current	l+	$RL = Infinite \overline{En} = 0V$		25	42	mA	
V- Supply Current	I-	$RL = Infinite \overline{En} = 0V$		-23	-42	mA	
INPUTS							
High Level Input Voltage	Vін		2.0			V	
Low Level Input Voltage	VIL				0.8	V	
Input Clamp Voltage	Viк	lı = -15 mA		-1.1	-1.8	V	
High Level Input Current	Ін	VIH = 2.4V		0.25	40	μA	
Low Level Input Current	lı∟	VIL = 0.4V	-200	-8.0		μA	
OUTPUTS							
High Level (Low Mode) Output Voltage	Vон	VIN = 0.8V $RL = Inf.$	5.0	5.3	6.0	V	
(EIA423A/V.10, EIA232E/V.28)		$\overline{En} = 0.8V$ RL = 3k	5.0	5.3	6.0	V	
		RL = 450	4.5	5.2	6.0	V	
Low Level (Low Mode) Output Voltage	Vol	VIN = 2.0V $RL = Inf.$	-5.0	-5.3	-6.0	V	
(EIA423A/V.10,EIA232E/V.28)		$\overline{En} = 0.8V$ RL = 3k	-5.0	-5.3	-6.0	V	
		RL = 450	-4.5	-5.2	-6.0	V	
Output Balance (EIA423A/V.10)	VBAL	RL = 450 VOH - VOL = VBAL		0.2	0.4	V	
High Level (High Mode) Output Voltage	Vон	VIN = 0.8V RL = Inf., MS+ = V+, MS- = V-	7.0	7.6	10	V	
(EIA232E/V.28)		En = 0.8V RL = 3k, MS+ = V+, MS- = V-	7.0	7.6	10	V	
Low Level (High Mode) Output Voltage	Vol	VIN = 2.0V RL = Inf., MS+ = V+, MS- =V-	-7.0	-7.7	-10	V	
(EIA232E, V.28)		En = 0.8V RL = 3k, MS+ = V+, MS- = V-	-7.0	-7.7	-10	V	
Off-State Output Current	loz	En = 2.0V, Vo = ±6V, V+ = 15V, V- = -15V	-100		100	μA	
Short-Circuit Current	los	$VIN = 0V, \overline{En} = 0V$	-25	-50		mA	
		$V_{IN} = 5V, \overline{En} = 0V$	25	40		mA	

AC ELECTRICAL CHARACTERISTICS: at | V+ | = | V - | = 10V, 0 < TA < +70°C, Ms+ = Ms- = 0V, TA =TJ.

PARAMETERS	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Output Slew Rate	tR	Rsra = 2k	6.65	9.5	12.3	V/µs
	tF	RL = 450, CL = 50pF	6.65	10	12.3	V/µs
Output Slew Rate	tR	Rsra = 10k	1.33	1.9	2.45	V/μs
	tF	RL = 450, CL = 50pF	1.33	2.2	2.45	V/μs
Propagation Output to	tHz	RSRA = 10k		0.3	1.0	μs
High Impedance	tLz	RL = 450, CL = 50pF		0.5	2.0	μs
Propagation High Impedance to	tzH	RSRA = 10k		6.0	17	μs
Output	tzL	RL = 450, CL = 50pF		7.0	17	μs

AC PARAMETER TEST CIRCUIT AND WAVEFORMS



AC CHARACTERISTICS



APPLICATION INFORMATION

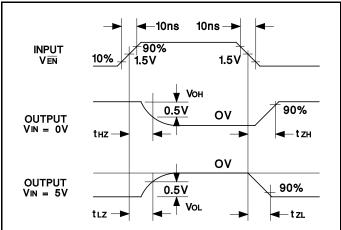
Slew Rate Programming

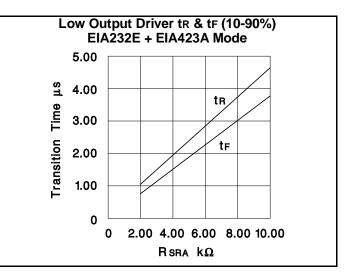
Slew rate for the UC5170C is set up by a single external resistor connected between the SRA pin and ground. Slew rate adjustments can be approximated by using the following formula:

$$V/\mu s = \frac{20}{R_{SRA}} (R_{SRA} \text{ in } k \Omega)$$

The slew rate resistor can vary between 2k and 10k which allows slew rates between 10 to $2.2V/\mu s$, respectively. The relationship between slew rate and RSRA is shown in the typical characteristics.

Waveshaping of the output lets the user control the level of interference (near-end crosstalk) that may be coupled to adjacent circuits in an interconnection. The recommended output characteristics for cable length and data rates can be found in EIA standard EIA423A +V.10. Approximations of these standards are given by the following equations:





Max. Data Rate = 300/t (For data rates 1k to 100k bit/s)

Max. Cable Length (feet) = 100 x t (Max. length 4000 feet)

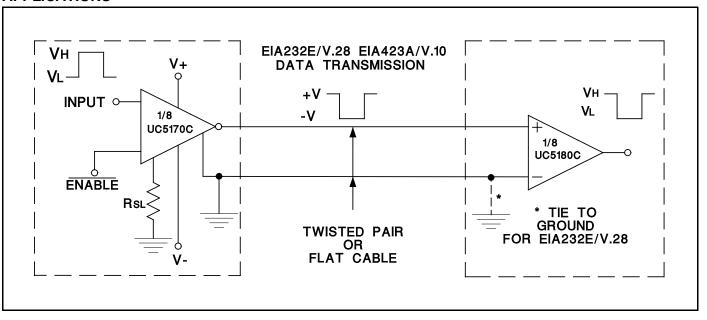
where t is the transition time from 10% to 90% of the output swing in microseconds. For data rates below 1k bit/s t may be up to 300 microseconds.

Output Voltage Programming

The UC5170C has two programmable output modes, either a low voltage mode which meets EIA423A, EIA232E/V.28/V.10 specifications, or the high output mode which meets the EIA232E, V.28 specifications.

The high output mode provides greater output swings, minimum of 3V below and supply rails for driving higher, attenuated lines. This mode is selected by connecting the mode select pins to their respected supplies, MS+ to V+ and MS- to V-.

The low output mode provides a controlled output swing and is accomplished by connecting both mode select pins to ground.



APPLICATIONS

SPECIFIC LAYOUT NOTES

The UC5170C layout must have bulk bypassing close to the device. Peak slew current is greater than 500mA when all eight drivers slew at once in the same direction. Some applications mount the UC5170C on a bulkhead or isolated plane for RFI/FCC/VDE reasons. If bulk bypassing is not used, the -10V supply may go above -8.5 volts, causing the slew rate control circuit to become unstable.

The UC5170C can have output oscillation at 100kHz if the +10V supply is applied before the -10V supply. This has been a problem in some terminal designs where the +10V was developed from the flyback, which can result in a 500ms difference in the application of the supplies at power up.

GENERAL LAYOUT NOTES

The drivers and receivers should be mounted close to the system common ground point, with the ground reference tied to the common point to reduce RFI/EMI.

Filter connectors or transzorbs should be used to reduce the RFI/EMI, protecting the system from static (ESD), and electrical overstress (EOS). A filter connector or capacitor will reduce the ESD pulse by 90% typically. A cable dragged across a carpet and connected to a system can easily be charged to over 25,00 volts. This is a metal to metal contact when the cable is connected to the system (no resistance), currents exceed 80 amps with less than a nanosecond rise time. A transzorb provides two functions, the device capacitance inherently acts as a filter capacitor, and the device clamps the ESD and EOS pulses which would pass through the capacitor and destroy the devices. The recommended transzorb for the UC5170C is P6KEIOCA.

*Transzorb is a trademark of General Semiconductor Industries.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Pa	ackage Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
UC5170CJ	OBSOLETE	CDIP	J	28		None	Call TI	Call TI
UC5170CN	OBSOLETE		UTR			None	Call TI	Call TI
UC5170CQ	ACTIVE	PLCC	FN	28	37	None	CU SNPB	Level-2-220C-1 YEAR
UC5170CQTR	ACTIVE	PLCC	FN	28	750	None	CU SNPB	Level-2-220C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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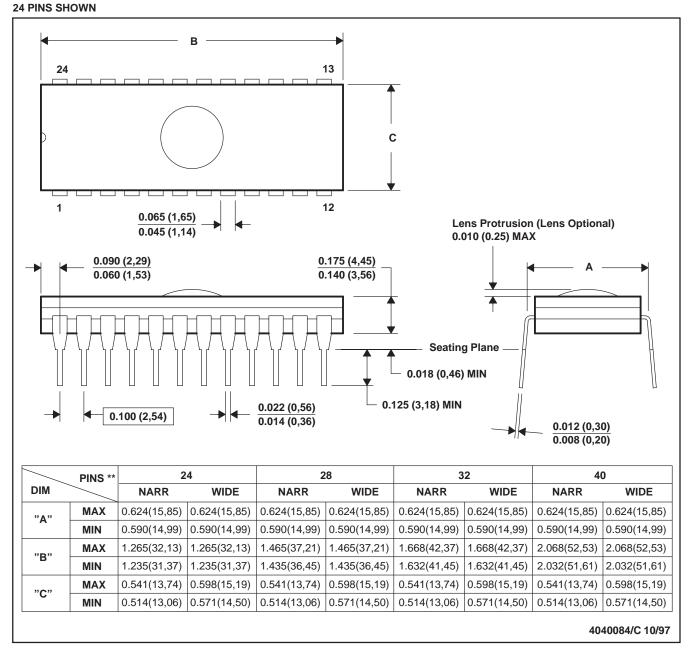
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MECHANICAL DATA

MCDI004A - JANUARY 1995 - REVISED NOVEMBER 1997

CERAMIC DUAL-IN-LINE PACKAGE

J (R-GDIP-T**)



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Window (lens) added to this group of packages (24-, 28-, 32-, 40-pin).
- D. This package can be hermetically sealed with a ceramic lid using glass frit.
- E. Index point is provided on cap for terminal identification.

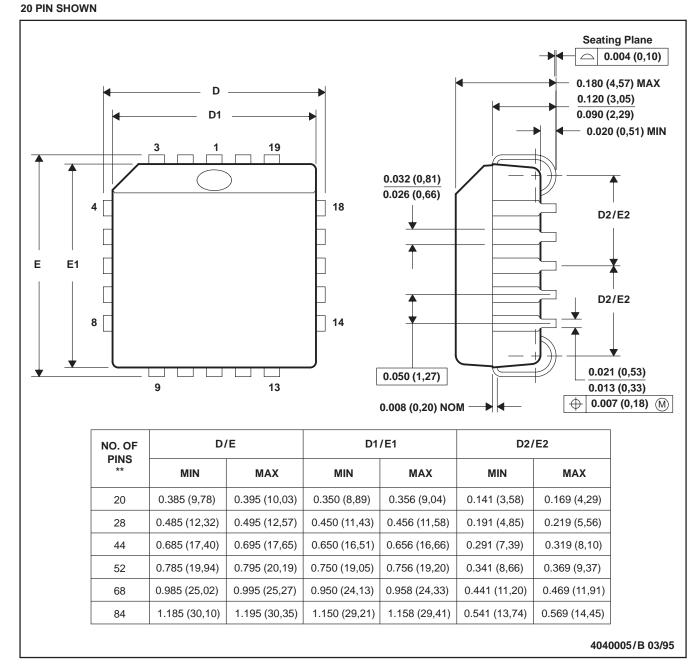


MECHANICAL DATA

MPLC004A - OCTOBER 1994

PLASTIC J-LEADED CHIP CARRIER

FN (S-PQCC-J**)



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Falls within JEDEC MS-018



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